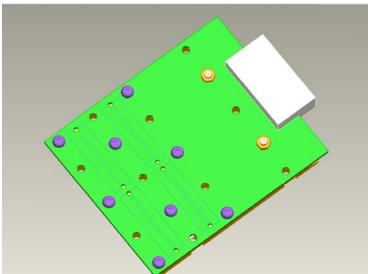
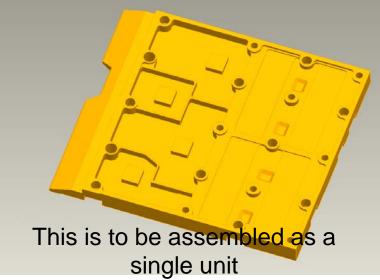
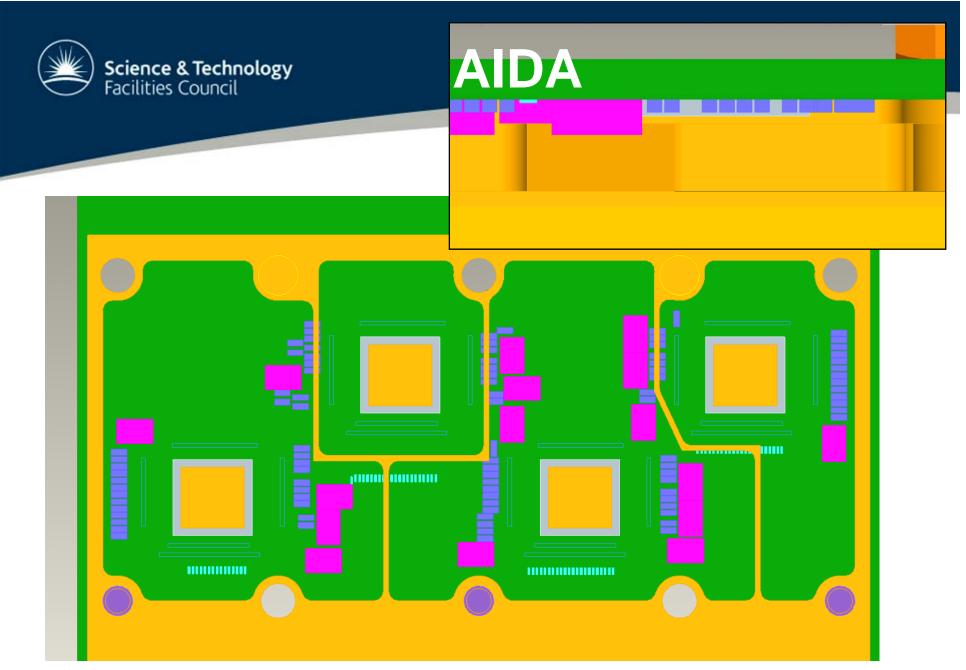


Light-tight area





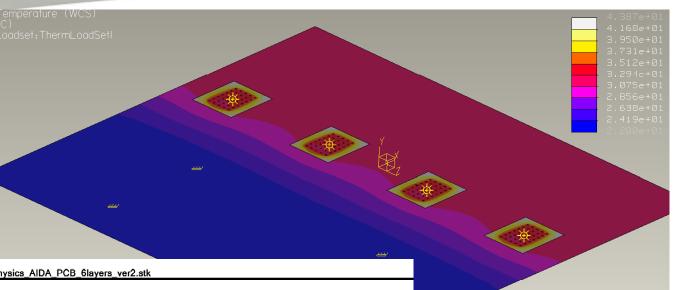






Max temp 44°C

Still have remainder of thermal path to consider

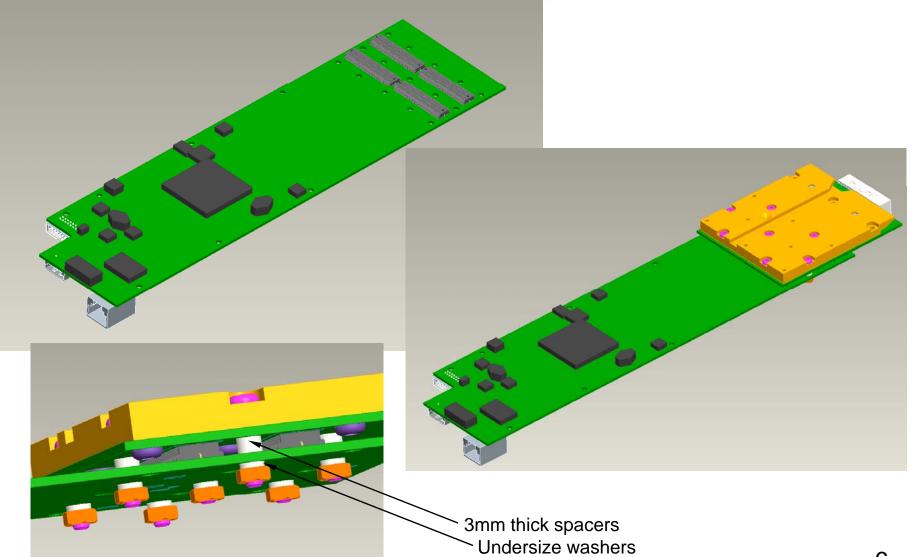


C:\Program Files\Polar\Speedstack\Smiths_Nuclear_Physics_AIDA_PCB_6layers_ver2.stk

Laye	ər	Stad	ck up	Supplier Description	Description	Stock Number	Base Thickness	Finish Thickness	13	Imp
					Soldermask				3.200	
1 2				0.203mm	STDFR4-LF		0.700 8.000 0.700	1.400 8.000 0.700	4.200	
				49N	49N-1080 noflow		2.760	2.760	4.200	
3	+10% / -10%			49N	49N-1080 noflow		2.760	2.760	4.200	
				49N	49N-1080 noflow		2.760	2.760	4.200	
				Copper Core	Copper		16.000	16.000		
	+			STDFR4-LF	STD1080		2.560	2.560	4.200	
	55			STDFR4-LF	STD1080		2.560	2.560	4.200	
				STDFR4-LF	STD1080		2.560	2.560	4.200	
4				0.203mm	STDFR4-LF		0.700 8.000	0.700 8.000	4.200	
5					Soldermask		0.700	1.400	3.200	

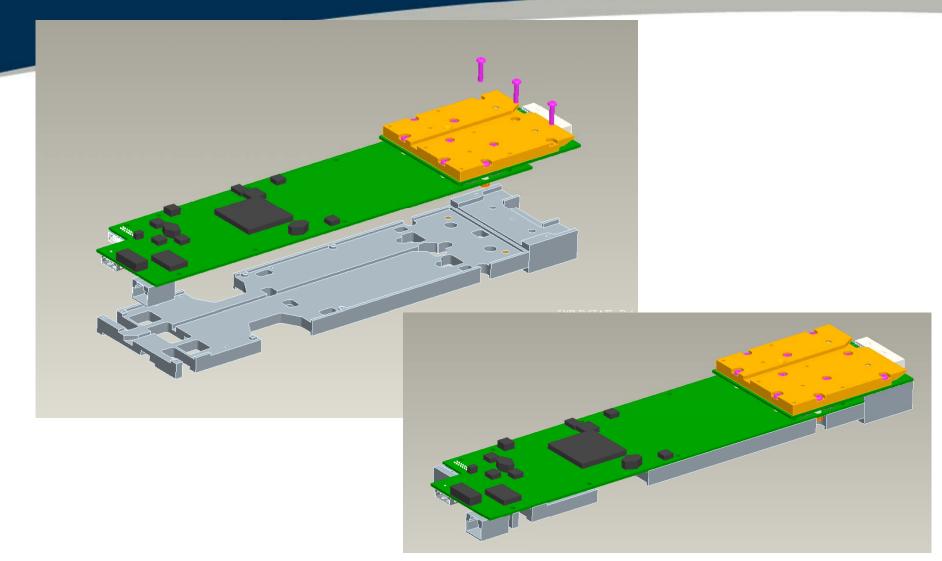






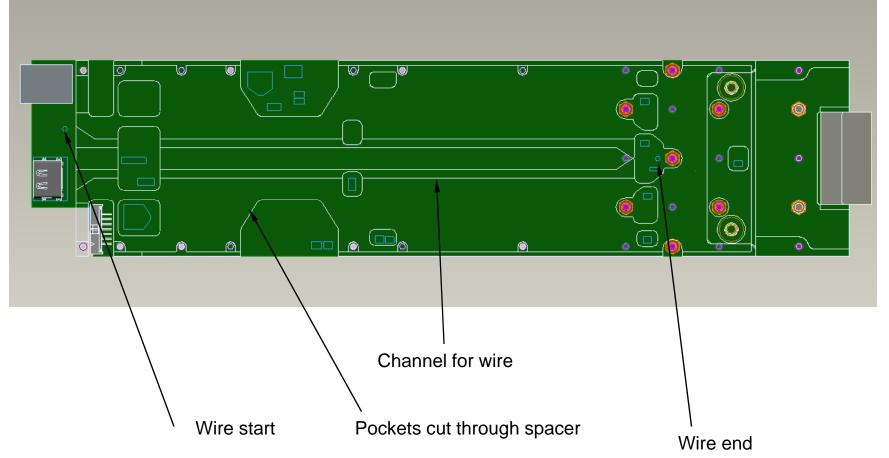






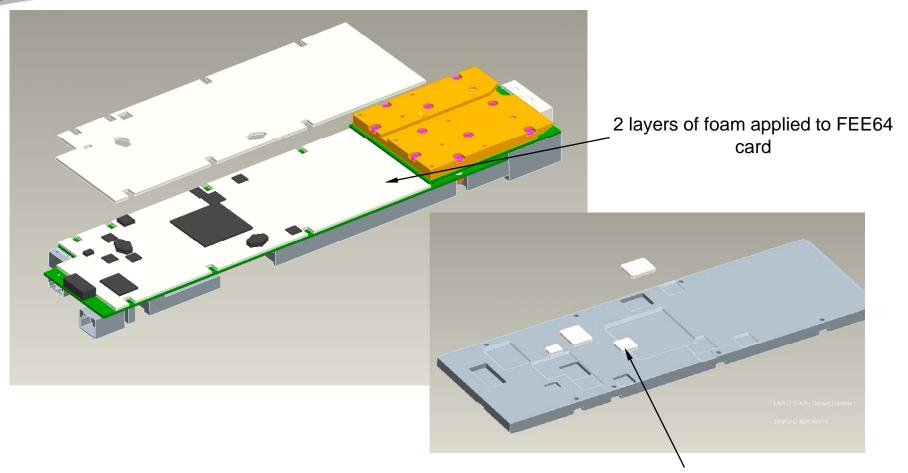








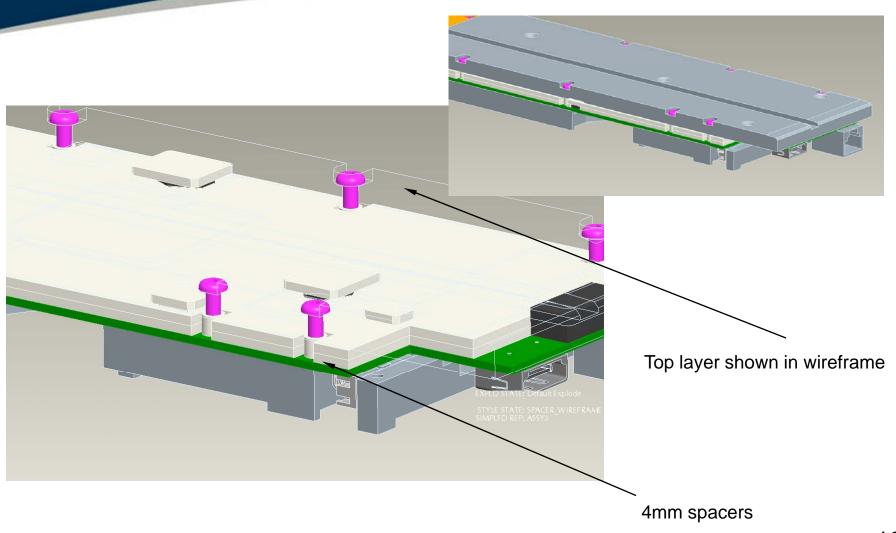




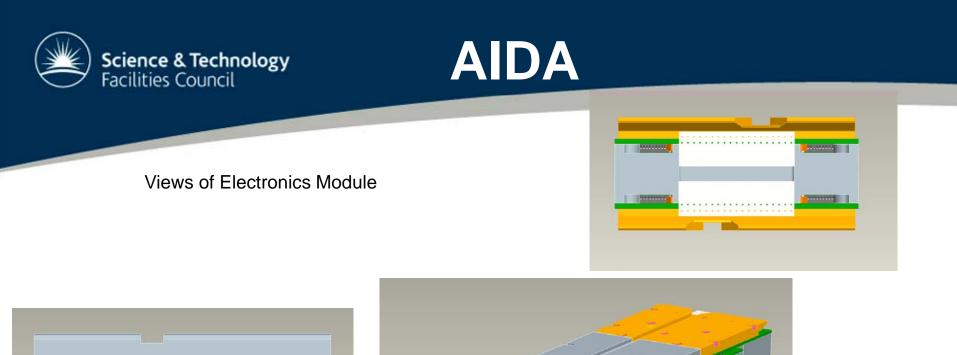
Foam applied to top plate

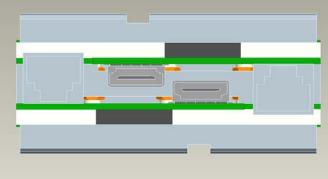


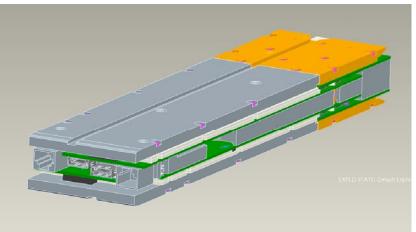




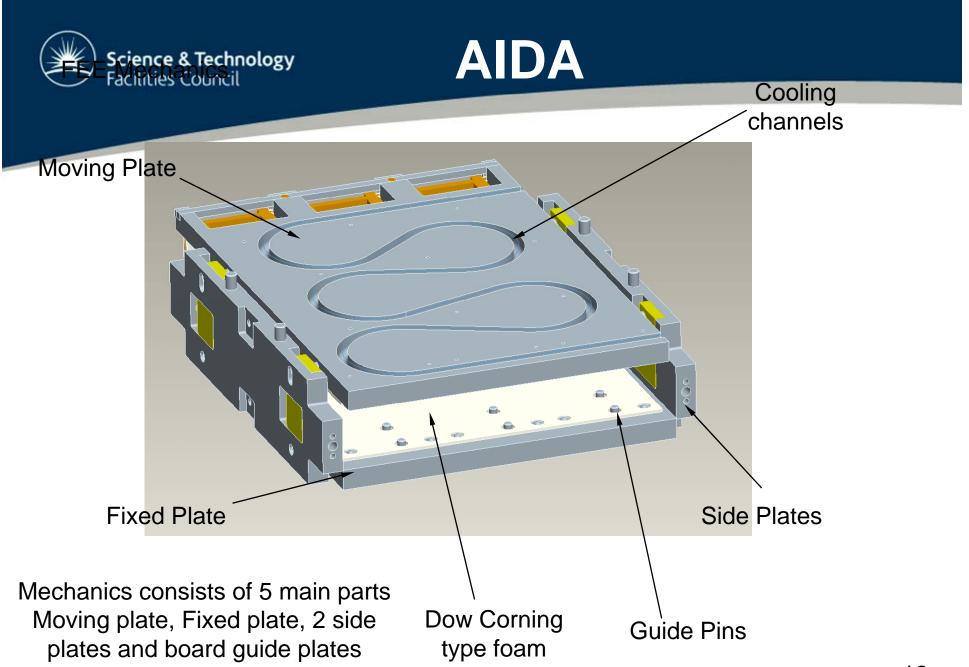
1 layer of uncompressed foam is 2.2mm 10





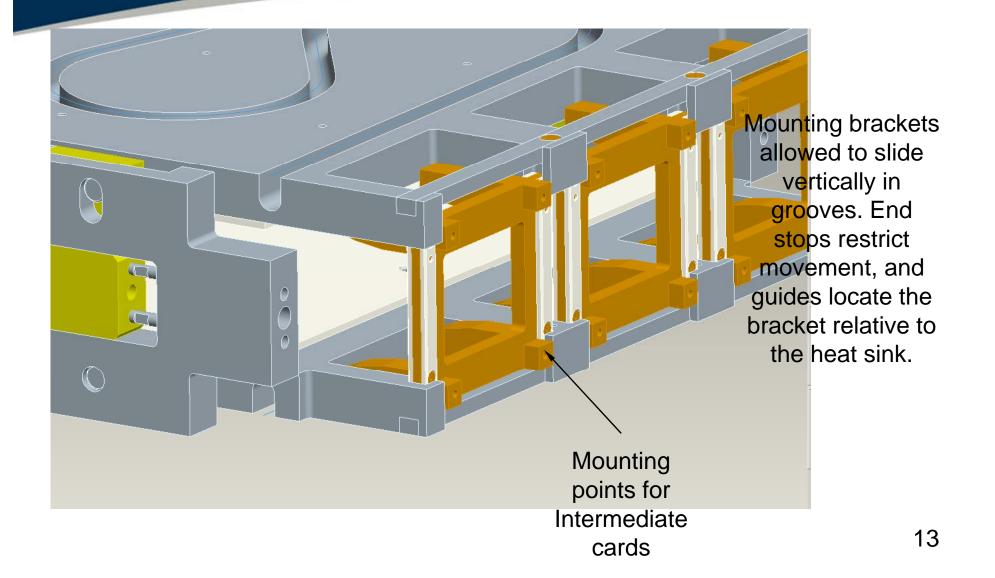








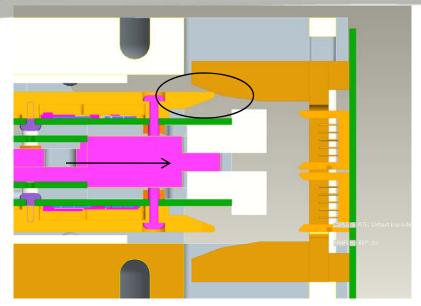


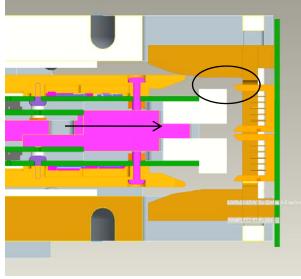


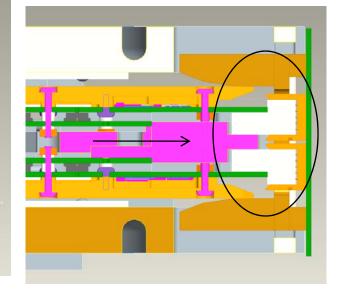


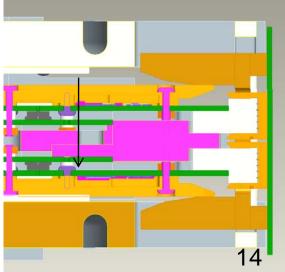


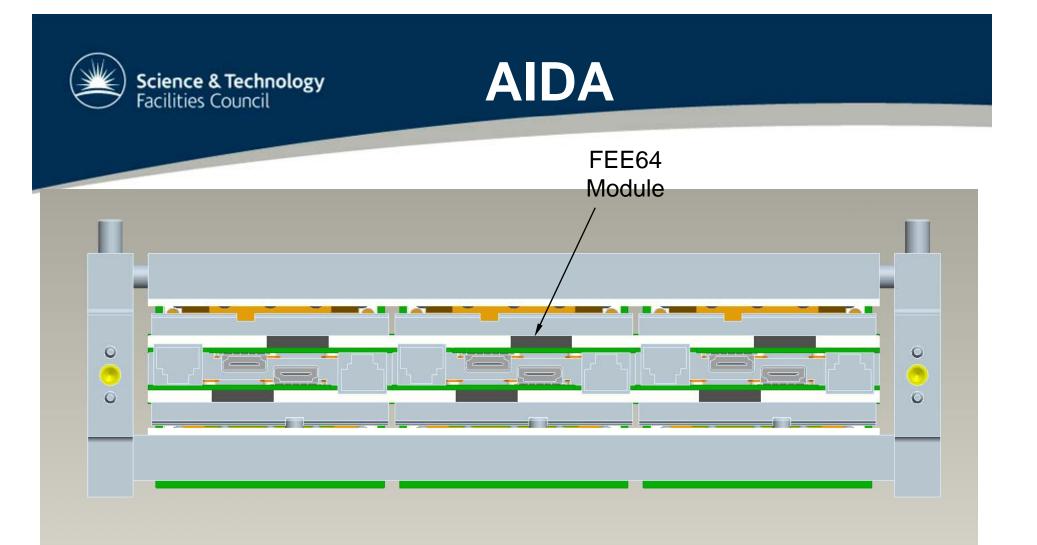












FEE64 board and mezzanine card 80mm wide.

Spacer plate 80mm wide, Top and bottom currently 78.





